



## SSC8623GSB

### N and P-Channel Enhancement Mode Power MOSFET

#### ➤ Features

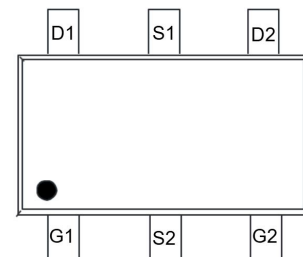
##### N-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
20V	$\pm 12V$	17m $\Omega$ @4V5	9A
		21m $\Omega$ @2V5	

##### P-Channel

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$ Typ.	$I_D$
-20V	$\pm 12V$	28m $\Omega$ @-4V5	-7A
		44m $\Omega$ @-2V5	

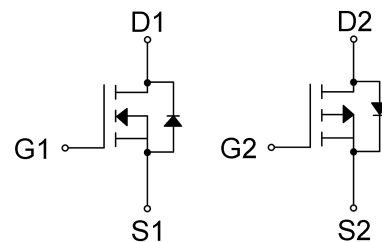
#### ➤ Pin configuration



**SOT-23-6L (Top View)**

#### ➤ Description

The SSC8623GSB uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.



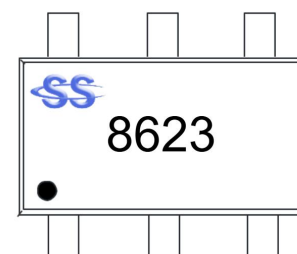
**Pin Configuration**

#### ➤ Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

#### ➤ Ordering Information

Device	Package	Shipping
SSC8623GSB	SOT-23-6L	3000/Reel



**Marking**



➤ **Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-to-Source Voltage		$V_{\text{DSS}}$	20	-20	V
Gate-to-Source Voltage		$V_{\text{GSS}}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current <sup>a</sup>	$T_A=25^{\circ}\text{C}$	$I_{\text{D}}$	9	-7	A
	$T_A=100^{\circ}\text{C}$		5	-4	A
Pulsed Drain Current <sup>b</sup>		$I_{\text{DM}}$	35	-26	A
Power Dissipation <sup>a</sup>		$P_{\text{DSM}}$	1.2	1.2	W
Power Dissipation <sup>c</sup>	$T_A=25^{\circ}\text{C}$	$P_{\text{D}}$	2.5	2.5	W
	$T_A=100^{\circ}\text{C}$		1	1	W
Operation junction temperature		$T_{\text{J}}$	-55 to 150	-55 to 150	$^{\circ}\text{C}$
Storage temperature range		$T_{\text{STG}}$	-55 to 150	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	N-Channel	P-Channel	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	105	105	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	50	50	

Note:

- The value of  $R_{\theta\text{JA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with  $T_A=25^{\circ}\text{C}$ .The value in any given application depends on the user is specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_{\text{D}}$  is based on  $T_{\text{J(MAX)}}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

**➤ N-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

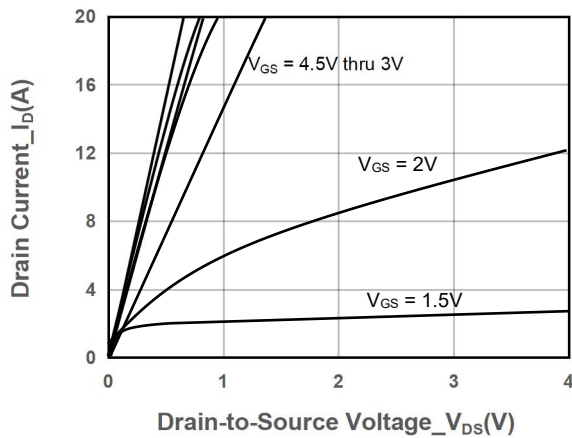
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	0.5	0.7	1	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4A		17	25	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A		21	30	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A			1.2	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		1201		pF
Output Capacitance	C <sub>OSS</sub>			112		
Reverse Transfer Capacitance	C <sub>RSS</sub>			100		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 3A		9		nC
Gate to Source Charge	Q <sub>GS</sub>			1.4		
Gate to Drain Charge	Q <sub>GD</sub>			2.4		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 3A, R <sub>GEN</sub> = 3Ω		5		ns
Rise Time	T <sub>r</sub>			15		
Turn-off Delay Time	T <sub>D(OFF)</sub>			22		
Fall Time	T <sub>f</sub>			7		

**➤ P-Channel Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

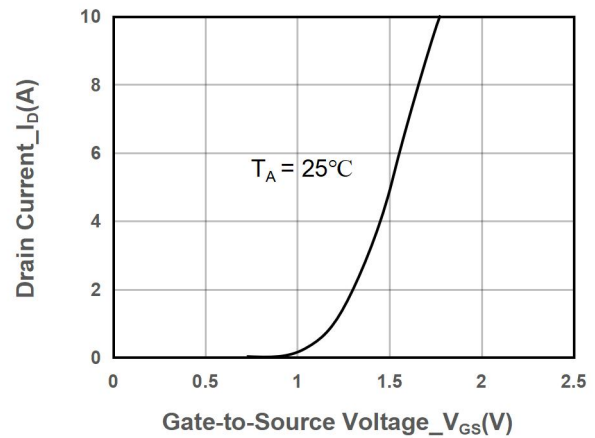
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-0.4	-0.75	-1	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4A		28	38	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3A		44	59	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V			-1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -2A		-0.82	-1.2	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz		1280		pF
Output Capacitance	C <sub>OSS</sub>			140		
Reverse Transfer Capacitance	C <sub>RSS</sub>			135		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -4A		15		nC
Gate to Source Charge	Q <sub>GS</sub>			2.3		
Gate to Drain Charge	Q <sub>GD</sub>			2.2		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, R <sub>L</sub> = 4Ω, R <sub>GEN</sub> = 1Ω, I <sub>D</sub> = -2.5A		10		ns
Rise Time	T <sub>r</sub>			30		
Turn-off Delay Time	T <sub>D(OFF)</sub>			20		
Fall Time	T <sub>f</sub>			11		



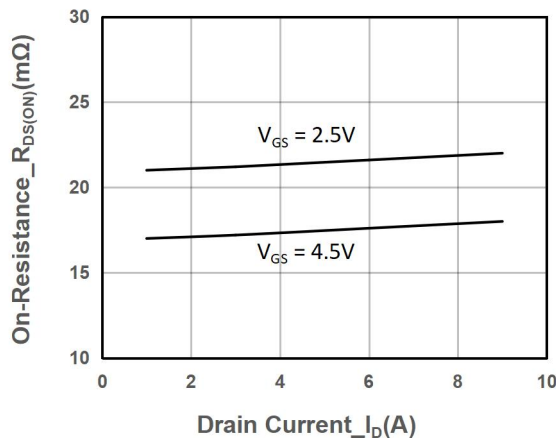
## ➤ N-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



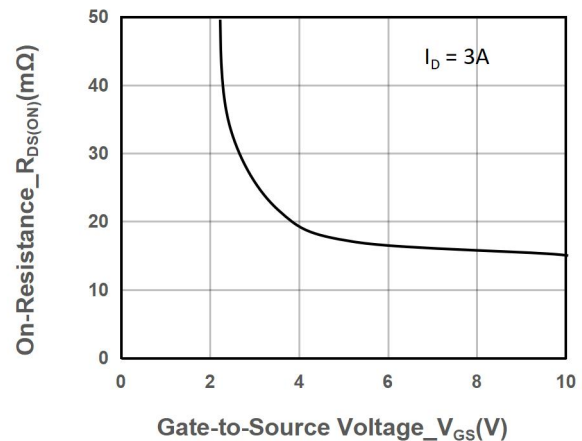
**Output Characteristics**



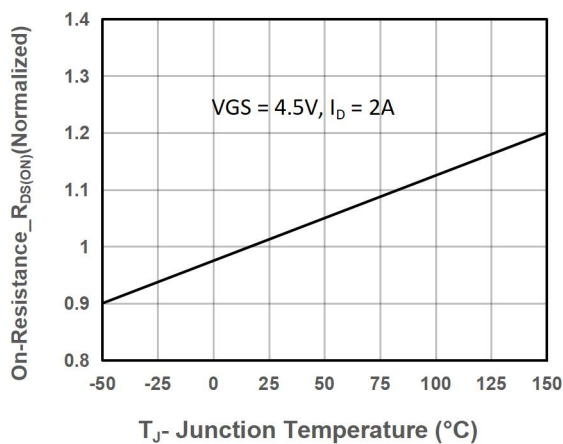
**Transfer Characteristics**



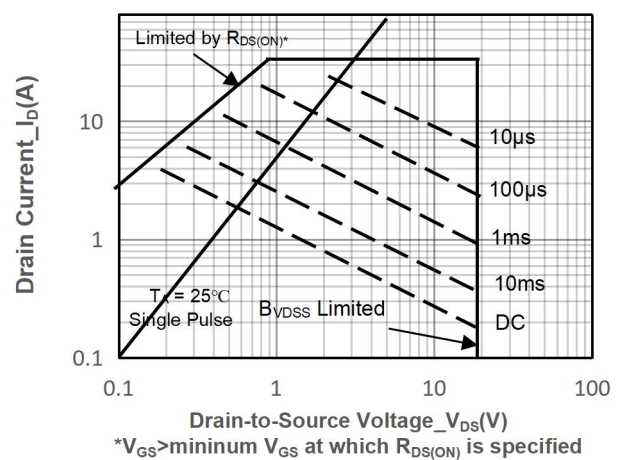
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



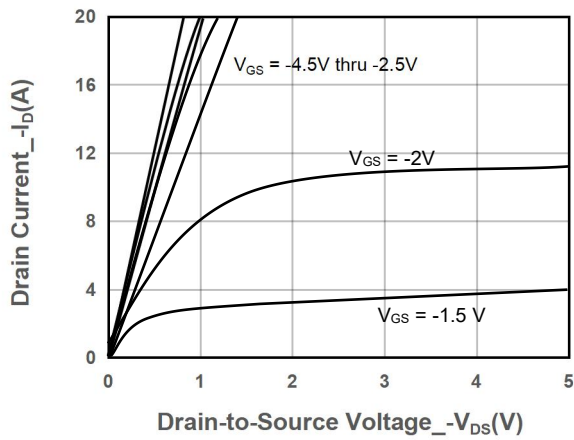
**On-Resistance vs. Junction Temperature**



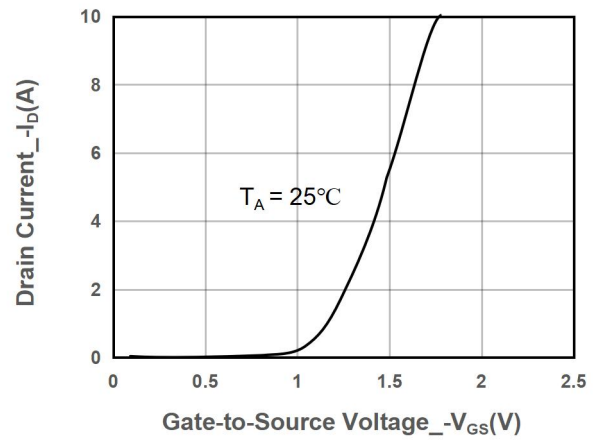
**Safe Operating Area vs. Junction-to-Ambient**



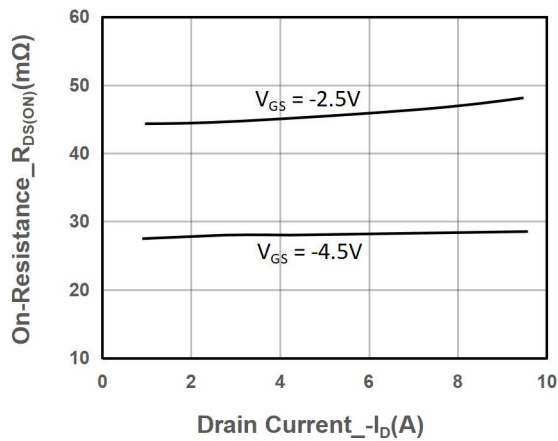
## ➤ P-Channel Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)



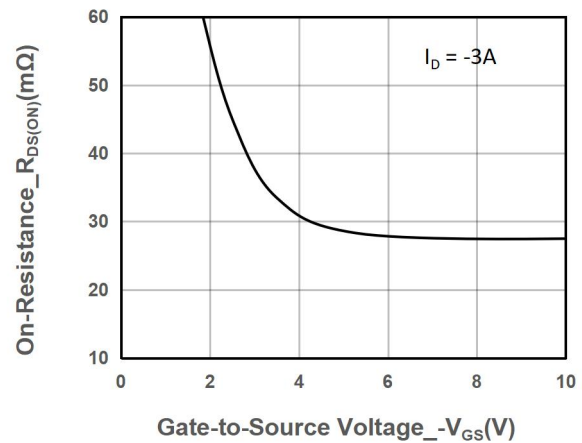
Output Characteristics



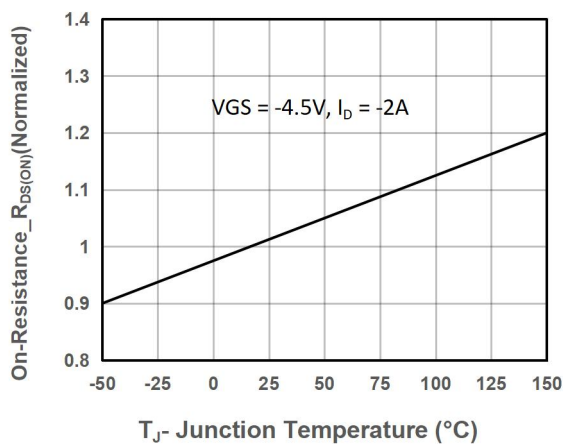
Transfer Characteristics



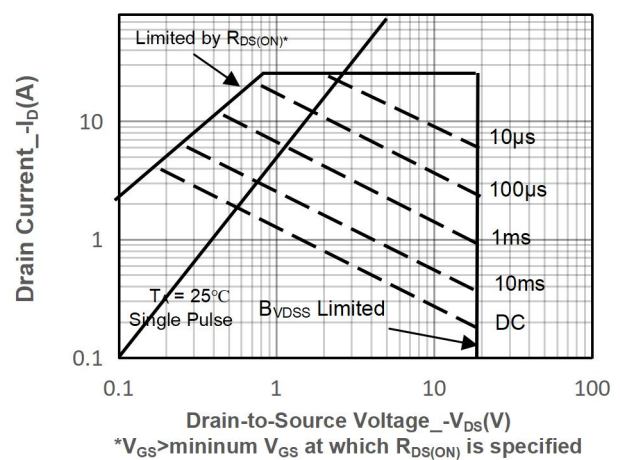
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

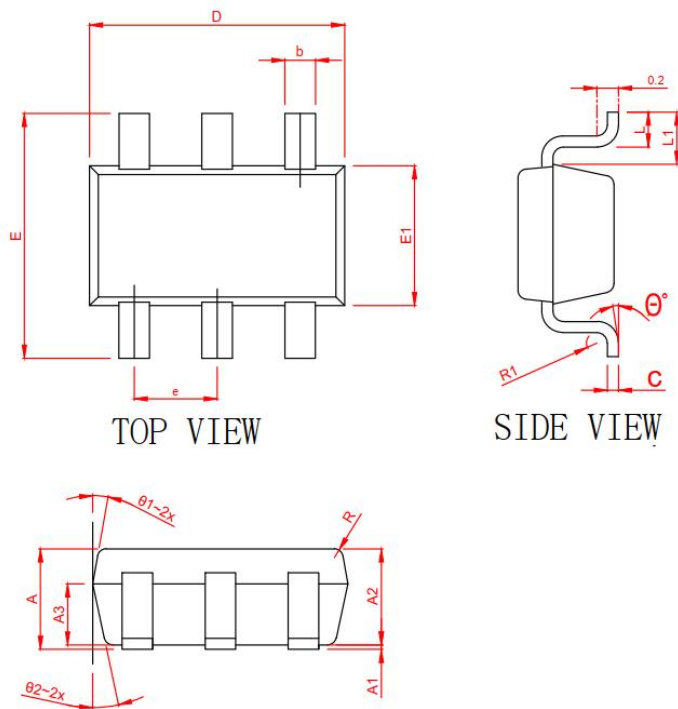


On-Resistance vs. Junction Temperature



Safe Operating Area vs. Junction-to-Ambient

## ➤ Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.06	1.15	1.24
* A1	0.01	0.05	0.09
* A2	1.05	1.10	1.15
A3	0.65	0.70	0.75
* b	0.30	0.35	0.45
* c	0.127REF		
* D	2.87	2.92	2.97
* E	2.72	2.80	2.88
* E1	1.55	1.60	1.65
* e	0.95BSC		
* L	0.32	0.40	0.48
* L1	0.55	0.60	0.65
R	0.10 REF		
R1	0.12 REF		
* θ	0	--	8°
θ1	8°	10°	12°
θ2	10°	12°	14°

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